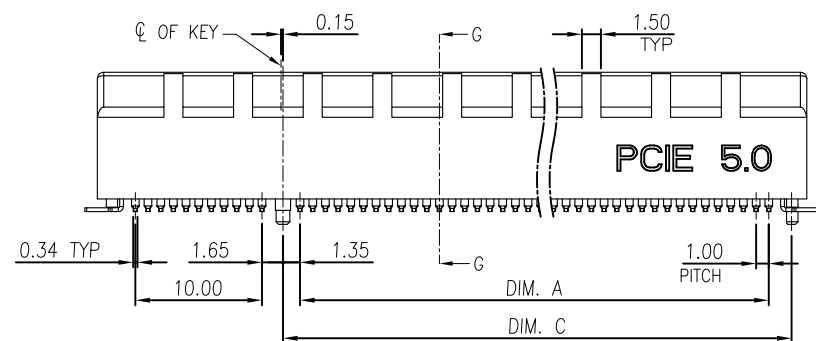
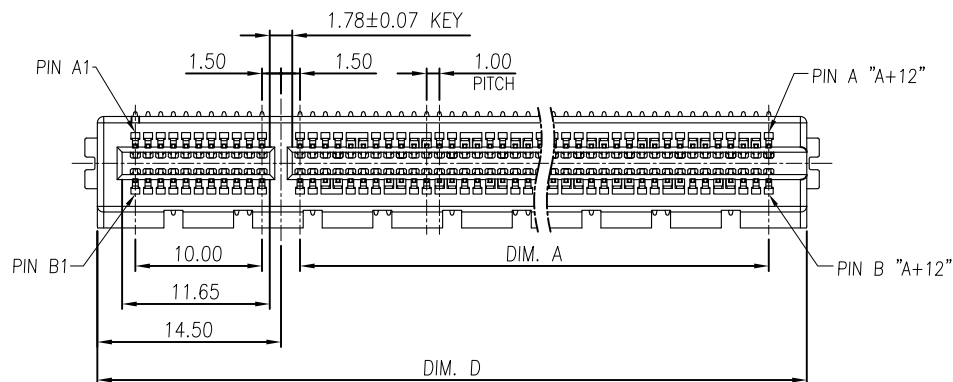
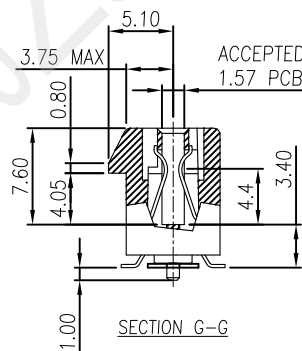
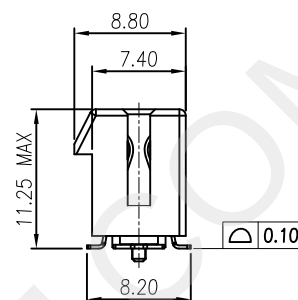


WITH RIDGE



DIMENSIONS				
POSITION	A±0.20	C±0.25	D±0.25	E±0.30
36	6.0	9.15	25.0	27.0
64	20.0	23.15	39.0	41.0
98	37.0	40.15	56.0	58.0
164	70.0	73.15	89.0	91.0

NOTES:

1. MATERIAL:

- 1.1 HOUSING: THERMOPLASTIC, HIGH TEMP, UL94V-0, COLOR:BLACK
- 1.2 CONTACTS: COPPER ALLOY.
- 1.3 PAD: COPPER ALLOY.
- 1.4 CAP: THERMOPLASTIC, HIGH TEMP, UL94V-0, COLOR: BLACK.

2. FINISH:

2.1 CONTACT:

SELECTIVE GOLD PLATING ON THE CONTACT AREA.
100μ" MIN. MATTE-TIN PLATING ON THE SOLDER TAILS,
50μ" MIN. NICKEL UNDERPLATING OVERALL.

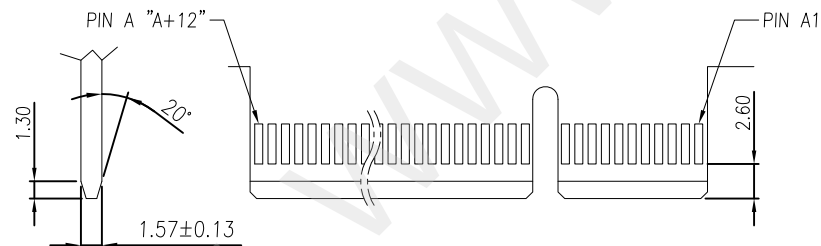
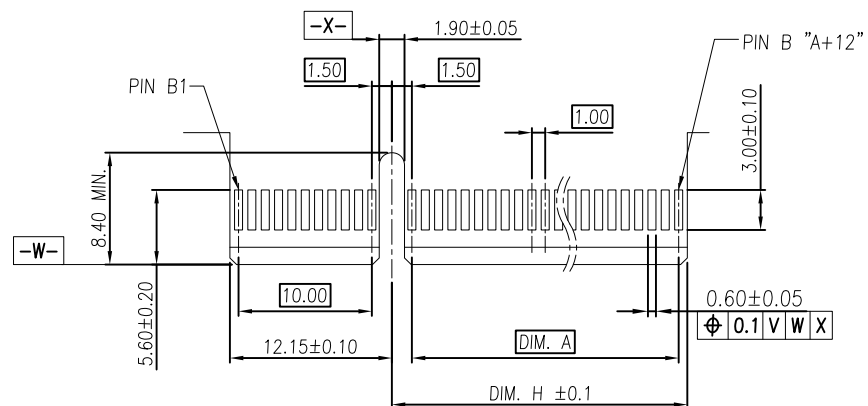
2.2 PAD:

100μ" MIN. MATTE-TIN PLATING WITH 50μ" MIN.
NICKEL UNDERPLATE OVERALL.



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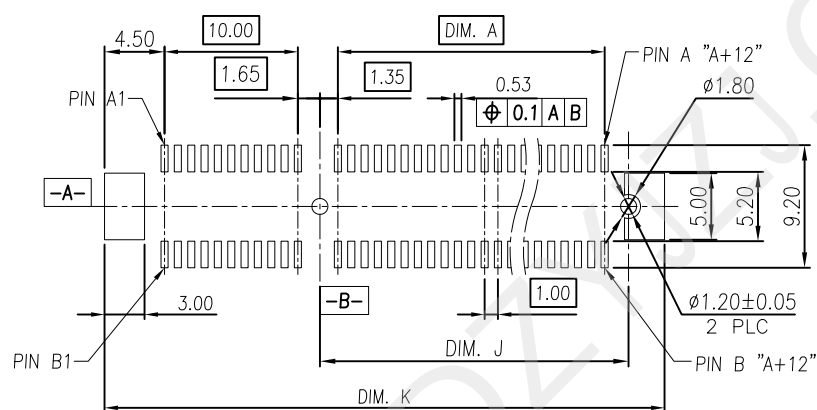
TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X' ±2" X.X' ±0.5"	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: PCI-E Gen 5.0 立贴 侧面开槽	
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO.	HYC58-PC1XX-112
	APPROVED BY: 邱敏	DATE : 2014-02-23	MOLD NO.	
			DRAW NO:	HYC-2606041051
SCALE:1:1	SIZE: A4		SHEET NO.	1 OF 1



SECONDARY (SOLDER) SIDE

I/O PANEL DIRECTION
PRIMARY (COMPONENT) SIDE

NOTES:
CHAMFER EDGE MUST BE FREE OF CUTTING BURRS

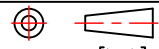


RECOMMENDED PCB LAYOUT
(COMPONENT SIDE)
TOLERANCE: ±0.05

POSITION	DIM. A	DIM. H	DIM. J	DIM. K
36	6.0	8.15	9.15	28.0
64	20.0	22.15	23.15	42.0
98	37.0	39.15	40.15	59.0
164	70.0	72.15	73.15	92.0



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TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X' ±2" X.X' ±0.5"	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: PCI-E Gen 5.0 立贴 侧面开槽	
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO.	HYC58-PCIXX-112
 UNIT: mm [inch] SCALE:1:1 SIZE: A4	APPROVED BY: 邱敏	DATE : 2014-02-23	DRAW NO:	HYC-2606041051
			SHEET NO.	1 OF 1